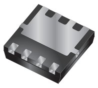
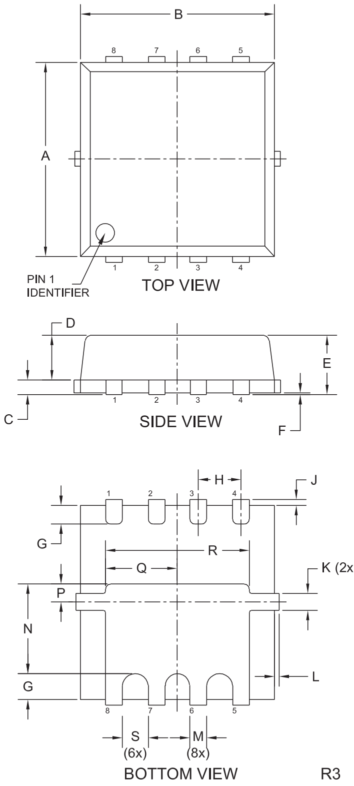
Package Details

TLM833 Case


Top View


Bottom View

Mechanical Drawing



DIMENSIONS				
	INCHES		MILLIMETERS	
SYMBOL	MIN	MAX	MIN	MAX
A	0.114	0.122	2.90	3.10
B	0.114	0.122	2.90	3.10
C	0.006	0.010	0.15	0.25
D	0.026	0.030	0.65	0.75
E	0.031	0.039	0.80	1.00
F	0.000	0.002	0.00	0.05
G	0.008	0.018	0.20	0.45
H	0.026		0.65	
J	---	0.005	---	0.125
K	0.007	0.012	0.17	0.30
L	---	0.005	---	0.125
M	0.011	0.015	0.29	0.39
N	0.049	0.057	1.25	1.45
P	0.006	0.014	0.15	0.35
Q	0.040	0.048	1.01	1.21
R	0.085	0.093	2.16	2.36
S	0.012	0.016	0.30	0.40

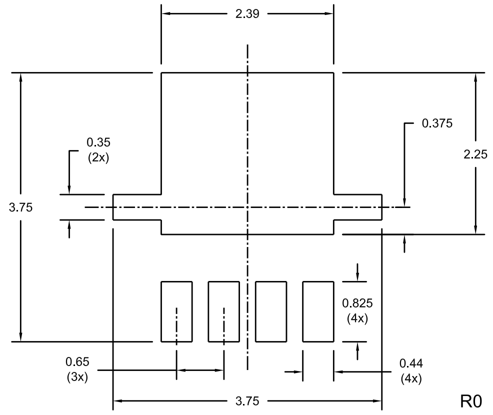
TLM833 (REV:R3)

Part Marking:
3-4 Character Alpha/Numeric Code

Lead Code:
Reference individual device datasheet.

Mounting Pad Geometry

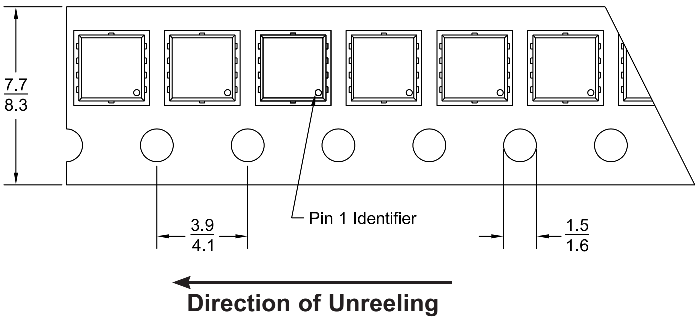
(Dimensions in mm)



R1 (4-March 2010)

Tape Dimensions and Orientation (Dimensions in mm)

Tape Width: 8mm



Devices are taped in accordance with Electronic Industries Association Standard EIA-481-1-A

Packaging Base

7” Reel = 3,000 pcs.

Reel Labeling Information

Each reel is labeled with the following information:
Central Part Number, Customer Part Number, Purchase Order Number, Quantity, Lot Number, Date Code, Ship Date and Marking Code.

Reel Packing Information

Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
7”	9	27,000	9x9x5	23x23x13	4	2
	18	54,000	9x9x9	23x23x23	8	4
	40	120,000	21x9x9	53x23x23	17	8
	108	324,000	27x9x17	69x23x43	45	21

Ordering Information

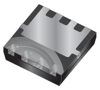
- For devices taped and reeled on 7” reels, add TR suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

R1 (4-March 2010)

Material Composition Specification

TLM833 Case


Top View


Bottom View

Device average mass . . . . **23 mg**

Fluctuation margin . . . . **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	2.6%	0.6	Si	7440-21-3	2.6%	0.6	26,035
bond wire	gold	1.04%	0.24	Au	7440-57-5	1.04%	0.24	10,414
leadframe	Cu alloy w/ silver plating	33.7%	7.77	Cu	7440-50-8	32.8%	7.56	328,040
				Fe	7439-89-6	0.79%	0.182	7,897
				Zn	7440-66-6	0.04%	0.009	391
				Ag	7440-22-4	0.07%	0.016	694
die attach	silver epoxy	1.04%	0.24	epoxy resin	Proprietary	0.22%	0.05	2,170
				Ag	7440-22-4	0.82%	0.19	8,244
encapsulation*	EMC GREEN	51.2%	11.8	silica (fused)	60676-86-0	43.52%	10.03	435,217
				epoxy resin	Proprietary	3.25%	0.75	32,544
				epoxy, cresol novolac	29690-82-2	1.02%	0.235	10,197
				phenol resin	9003-35-4	3.25%	0.75	32,544
				carbon black	1333-86-4	0.15%	0.034	1,475
plating	matte tin	10.41%	2.4	Sn	7440-31-5	10.41%	2.4	104,140

*EMC GREEN molding compound is Halogen-Free.

R2 (3-June 2011)